

Special Issue

Thermal Management of Power Electronic Components and Systems

Message from the Guest Editors

The aim of this Special Issue is to provide a forum for a discussion of the advances and new technology development in the thermal management of power electronics. Papers dealing with the aforementioned limitations and challenges are invited. Also relevant are studies about energy efficiency, heat transfer processes (especially studied by an approach that couples experimental measurements with theoretical/numerical modeling), as well as the use of nanofluids, enhanced surfaces, nanocoatings, and phase change materials. All original research papers or letters and short reviews are welcome. We cordially invite a contribution from you (i.e., either a research paper, review article or communication), for peer review and possible publication to this Special Issue. Details can be found: [Thermal Management of Power Electronic Components and Systems](#)

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Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

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